



## IPC Printed Circuits Expo<sup>®</sup>, APEX<sup>®</sup> and the Designers Summit

CONFERENCE & EXHIBITION: Tuesday–Thursday, April 1–3, 2008

MEETINGS: March 29–April 3, 2008

Mandalay Bay Resort & Convention Center, Las Vegas

### S22 Embedded Devices I

Wednesday, 4/2/2008

1:30 PM - 3:30 PM

Moderator: *Happy Holden, Mentor Graphics*

What are the unique advantages of embedded devices? What do they mean to design and performance? This session is the first of two that will discuss the latest advances in materials and design of embedded devices.

- Business Case for Multiple Sheet Resistivities for Thin Film Embedded Resistor Packaging Applications
  - Rocky Hilburn, Ticer Technologies
- The Embedded Passives Journey
  - Bill Devenish, Harris Corp.
- The Study Of High Density Pcb Reliability
  - Huang Mingli, Huawei Technologies Co., Ltd., China
- Laser Micromachining of Nanocomposite-Based Flexible Embedded Capacitors
  - Rabindra Das, Endicott Interconnect Technologies, Inc.